

ASSP

IF Band PLL Frequency Synthesizer

MB15C101

■ DESCRIPTION

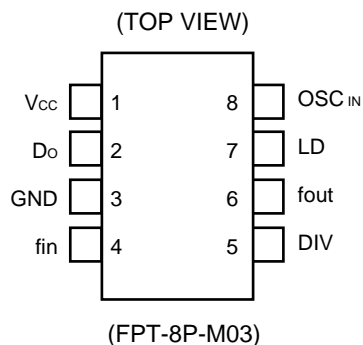
The Fujitsu Semiconductor MB15C101 is an exclusive Intermediate Frequency (IF) band Phase Locked Loop (PLL) frequency synthesizer with pulse swallow operation. The reference divider and comparison divider have fixed divide ratios, so that it is not required to set the divide ratios by a microcontroller externally.

It operates with a supply voltage of 3.0 V Typ and dissipates 1.0 mA Typ (270MHz) of current realized through the use of Fujitsu Semiconductor's CMOS technology.

■ FEATURES

- Low power supply current: $I_{CC} = 1.0 \text{ mA Typ}$ ($V_{CC} = 3 \text{ V}$, 270 MHz)
- Pulse swallow function; Prescaler: 16/17
- Setting frequency (Selectable by DIV input.)
 - $f_{osc} = 19.2 \text{ MHz}$, $f_{IF} = 233.15 \text{ MHz}$ (DIV = "H")
 - $f_{osc} = 19.2 \text{ MHz}$, $f_{IF} = 259.20 \text{ MHz}$ (DIV = "L")
- Lock detector
- Low power supply voltage: $V_{CC} = 2.4 \text{ V Min}$
- Wide operating temperature: $T_a = -40 \text{ to } +85^\circ\text{C}$

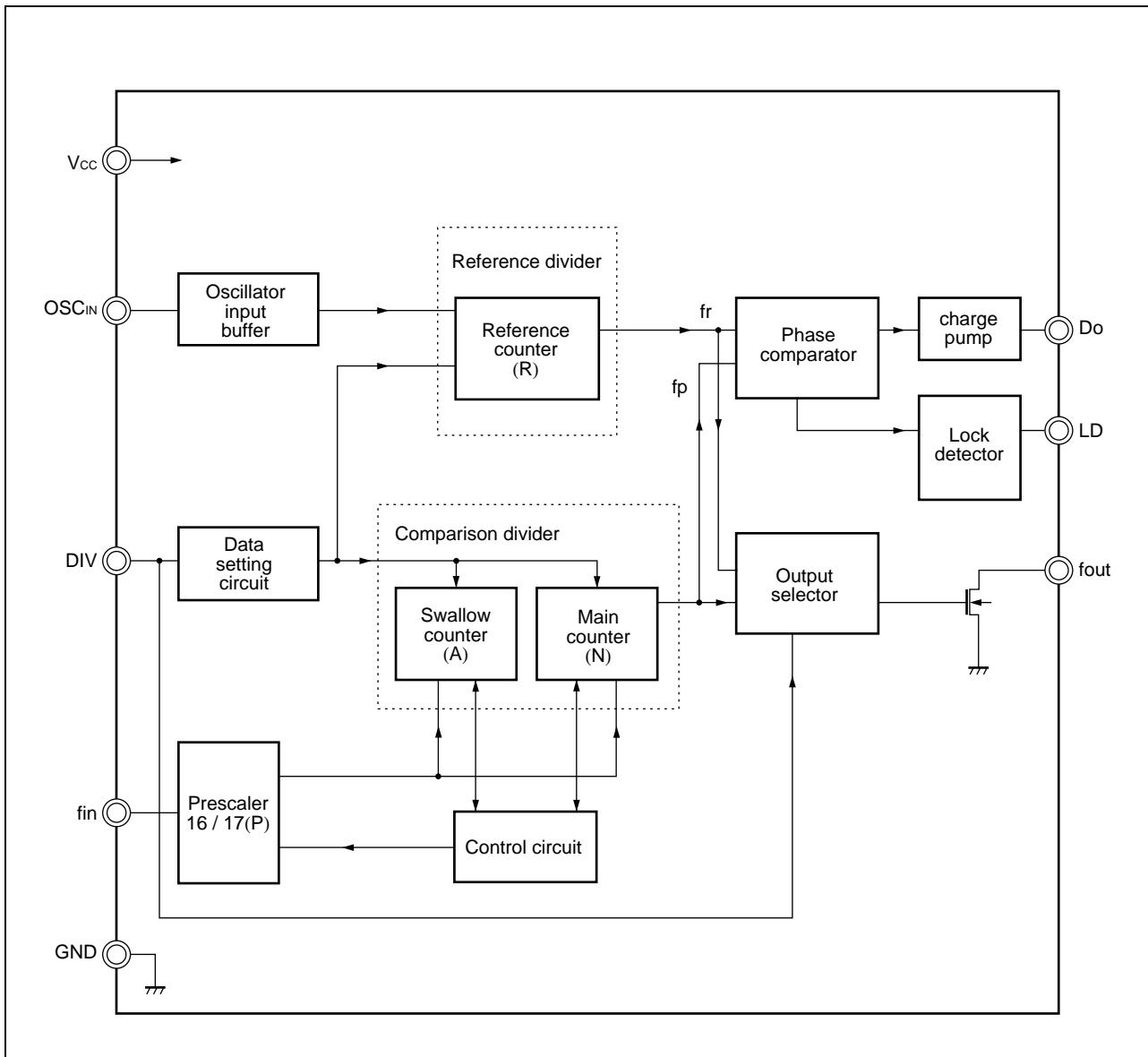
■ PIN ASSIGNMENT



■ PIN DESCRIPTIONS

Pin No. SSOP-8	Pin name	I/O	Descriptions
1	V _{CC}	–	Power supply voltage input pin (2.4 V to 3.6 V).
2	Do	O	Charge pump output
3	GND	–	Ground
4	fin	I	Prescaler input. Connection should be with AC coupling.
5	DIV	I	Divide ratio switching input. Two kinds of divide ratios are selectable by DIV input "H" or "L".
6	fout	O	Test purpose output. This pin is an open drain output so that should be left open usually.
7	LD	O	Lock detector output. LD = H ; Lock LD = L ; Unlock
8	OSC _{IN}	I	Reference counter input. Connection should be with AC coupling.

■ BLOCK DIAGRAM



■ FUNCTIONAL DESCRIPTIONS

Two different frequencies can be selected by Div input “H” or “L”.
The divide ratios are calculated using the following equation:

$$f_{vco} = \{(P \times N) + A\} \times f_{osc} \div R \quad (A < N)$$

Symbol	Description	DIV = “H”	DIV = “L”
f_{vco}	Output frequency of external VCO	233.15 MHz	259.20 MHz
f_{osc}	Reference oscillation frequency	19.2 MHz	19.2 MHz
N	Divide ratio of the main counter	291	33
A	Divide ratio of the swallow counter	7	12
P	Preset divide ratio of dual modulus prescaler	16/17	16/17
R	Divide ratio of the reference counter	384 (fr = 50 kHz)	40 (fr = 480 kHz)

■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating		Unit
		Min	Max	
Power supply voltage	V_{CC}	-0.5	+4.0	V
Input voltage	V_I	-0.5	$V_{CC} + 0.5$	V
Output voltage	V_O	-0.5	$V_{CC} + 0.5$	V
Output current	I_O	0	+5	mA
Storage temperature	T_{stg}	-55	+125	°C

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Value			Unit
		Min	Typ	Max	
Power supply voltage	V_{CC}	2.4	3.0	3.6	V
Input voltage	V_{IN}	GND	–	V_{CC}	V
Operating temperature	T_a	-40	–	+85	°C

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

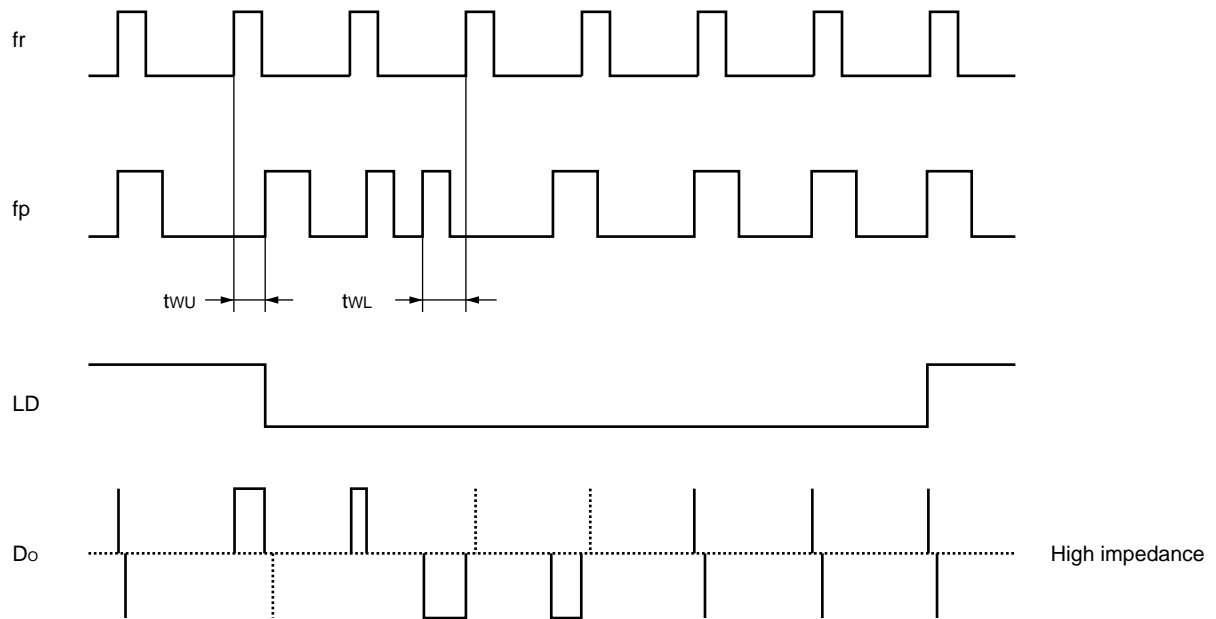
No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

■ ELECTRICAL CHARACTERISTICS

Recommended operating conditions unless otherwise noted.

Parameter	Symbol	Condition	Value			Unit	
			Min	Typ	Max		
Power supply current	I _{CC}	PLL is locked.(270 MHz) T _a = +25°C, V _{CC} = 3.0 V	0.1	1.0	2.0	mA	
Operating frequency	f _{in}	AC coupling by 1000 pF capacitor	50	–	270	MHz	
	OSC _{IN}	AC coupling by 1000 pF capacitor	3	–	26	MHz	
Input sensitivity	f _{in}	AC coupling by 1000 pF capacitor	–10	–	2	dBm	
	OSC _{IN}	AC coupling by 1000 pF capacitor	0.5	–	–	V _{pp}	
Input voltage	DIV	V _{IH}	–	0.7× V _{CC}	–	V	
		V _{IL}	–	–	0.3× V _{CC}	V	
Input current	DIV	I _{IH}	–	–	1.0	μA	
		I _{IL}	–	–1.0	–	μA	
Input current	OSC _{IN}	I _{OSC}	–100	–	+100	μA	
Output voltage	Do	V _{OH}	V _{CC} = 3.0 V, I _{OH} = –0.3 mA	2.6	–	–	V
		V _{OL}	V _{CC} = 3.0 V, I _{OL} = 0.3 mA	–	–	0.4	V
Output current	Do	I _{OH}	V _{CC} = 3.0 V, V _{OH} = 2 V, T _a = +25°C	–	–6.0	–	mA
		I _{OL}	V _{CC} = 3.0 V, V _{OL} = 1 V, T _a = +25°C	–	6.0	–	mA
High impedance cut off current	Do	I _{OFF}	0 ≤ V _{DO} ≤ V _{CC}	–	–	3.0	nA

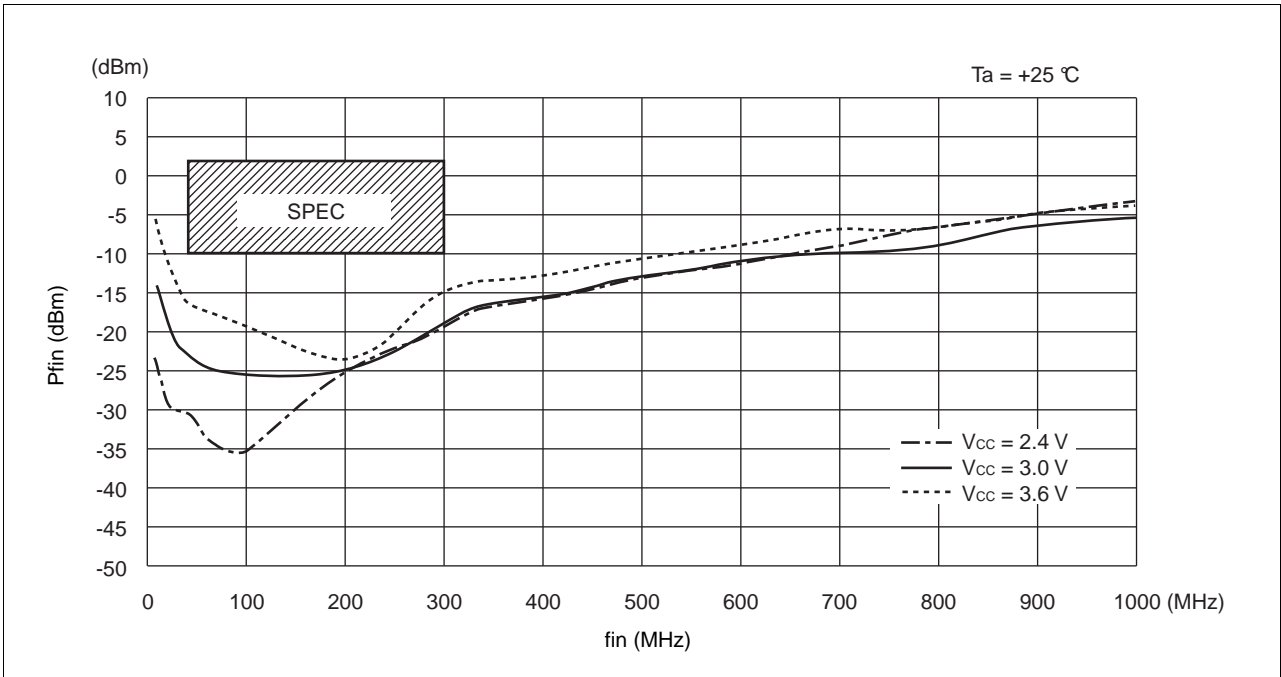
■ PHASE DETECTOR TIME CHART



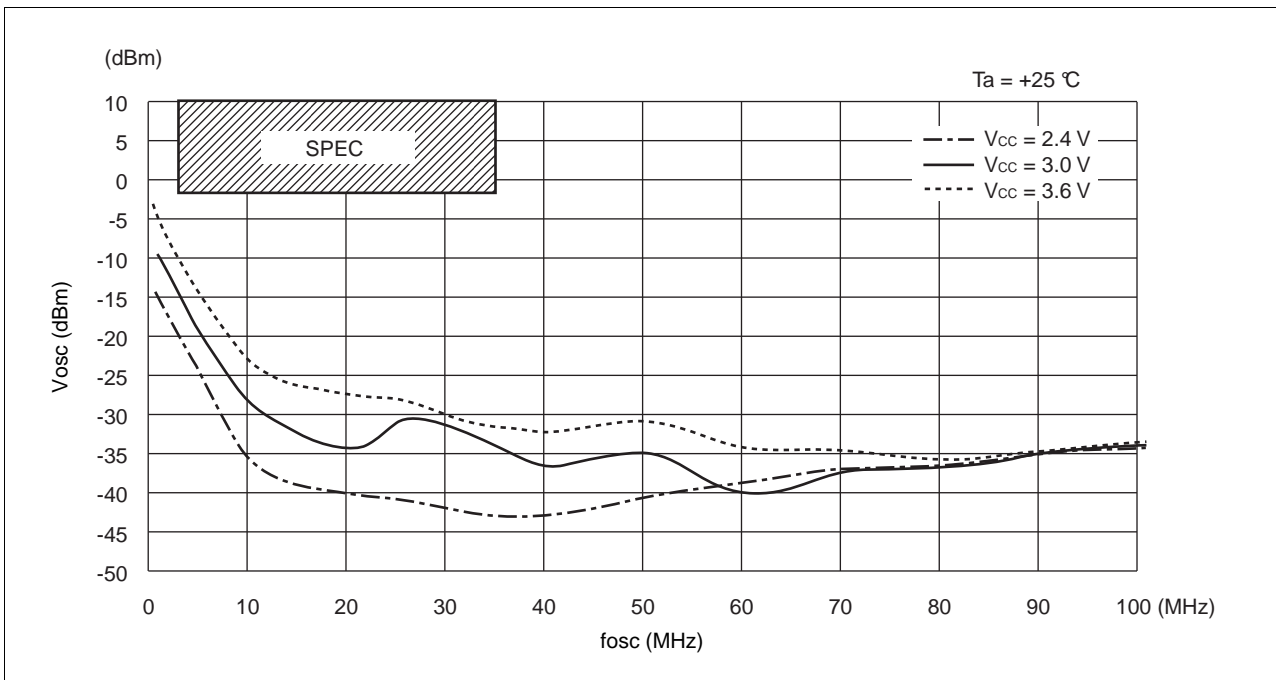
- Notes
- Phase error detection range: -2π to $+2\pi$
 - LD output becomes low when phase is t_{WU} or more. LD output becomes high when phase error is t_{WL} or less and continues to be so for three cycles or more.
 - Pulses on Do output signal during locked state are output to prevent dead zone.
 - t_{WU} and t_{WL} depend on OSC_{IN} input frequency.
 - $t_{WU} \geq 8/f_{osc}$ (s) (e. g. $t_{WU} \geq 625.0ns$, $f_{osc} = 12.8$ MHz)
 - $t_{WL} \leq 16/f_{osc}$ (s) (e. g. $t_{WL} \leq 1250.0ns$, $f_{osc} = 12.8$ MHz)

TYPICAL CHARACTERISTICS

1. f_{in} Input Sensitivity

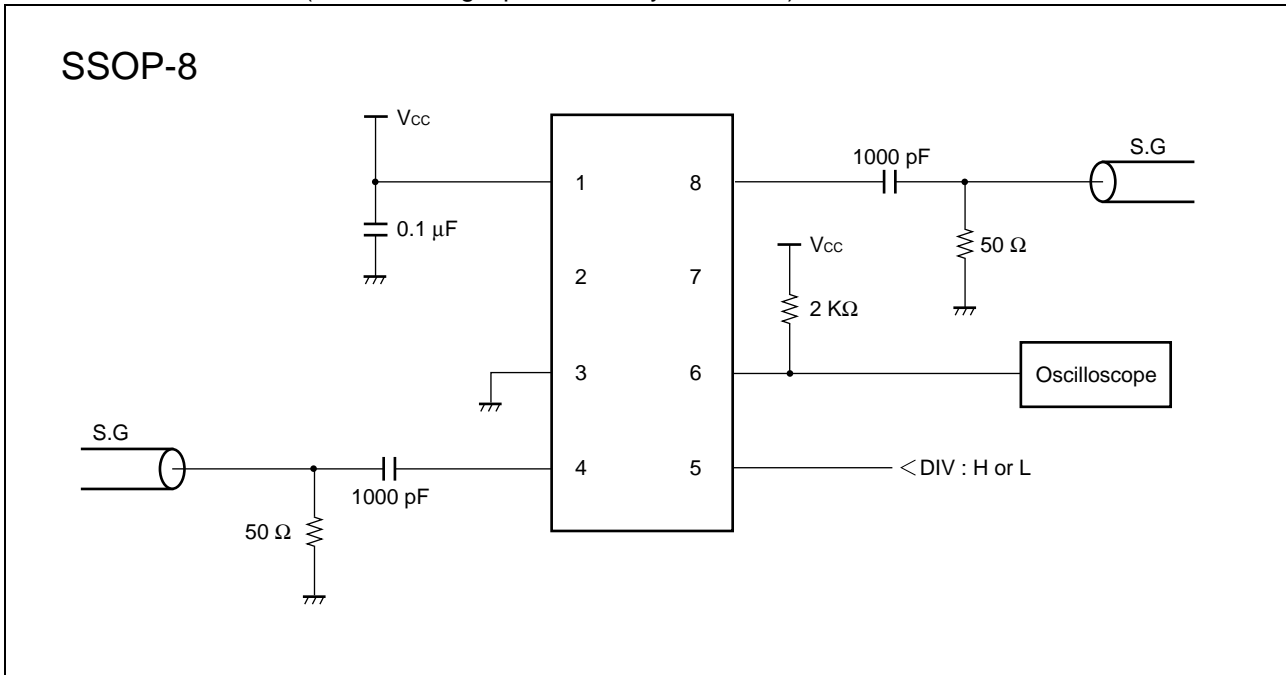


2. OSC_{IN} Input Sensitivity

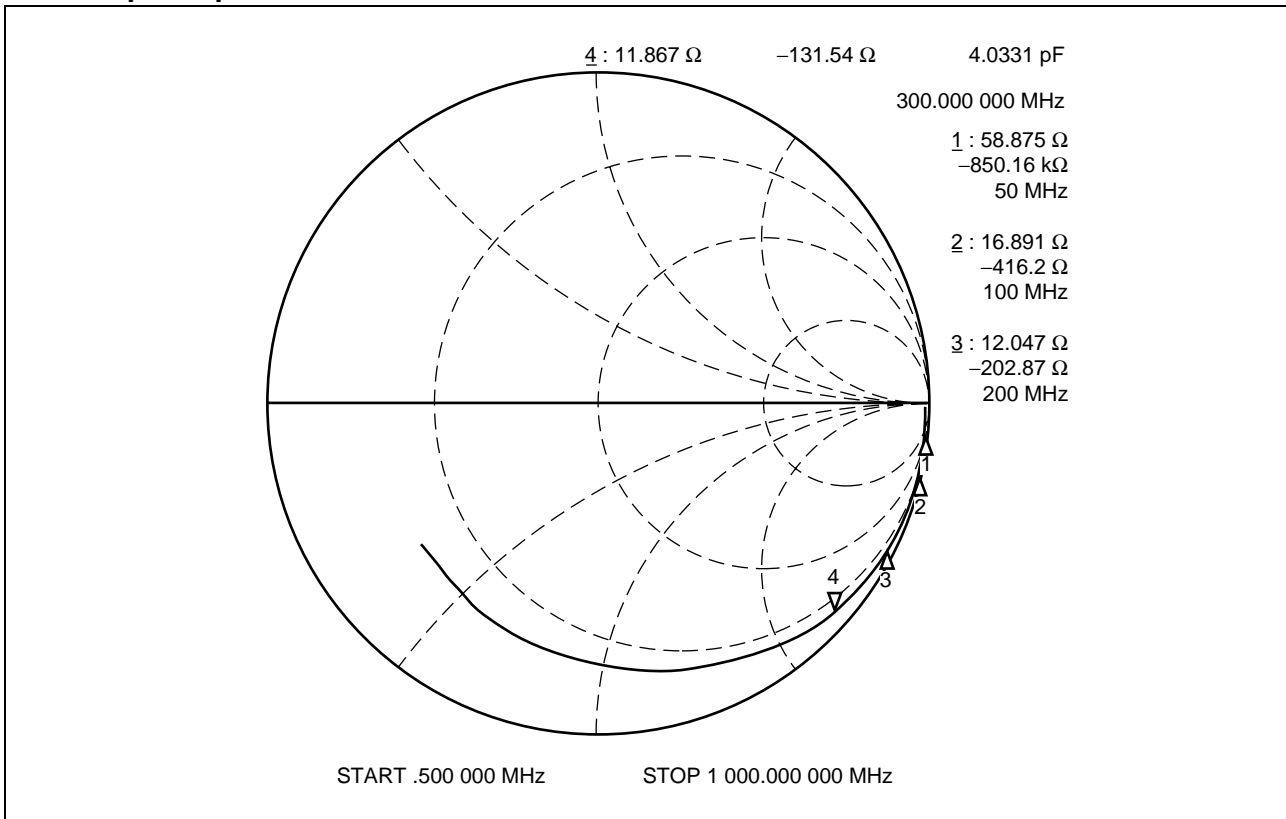


MB15C101

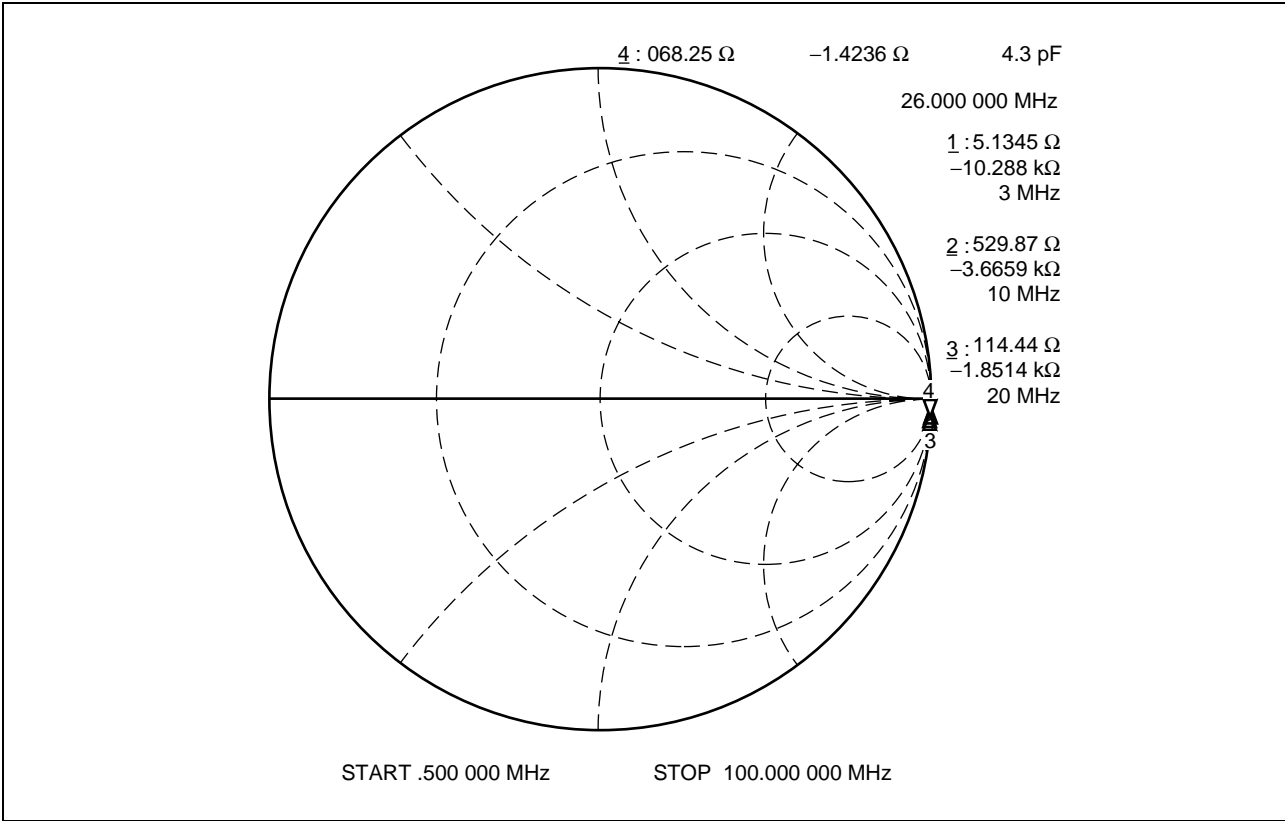
- Measurement Circuit (for measuring input sensitivity fin/OSC_{IN})



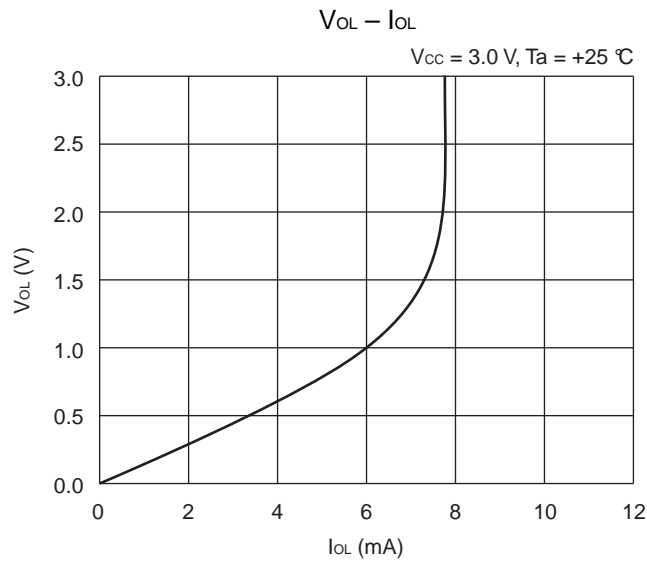
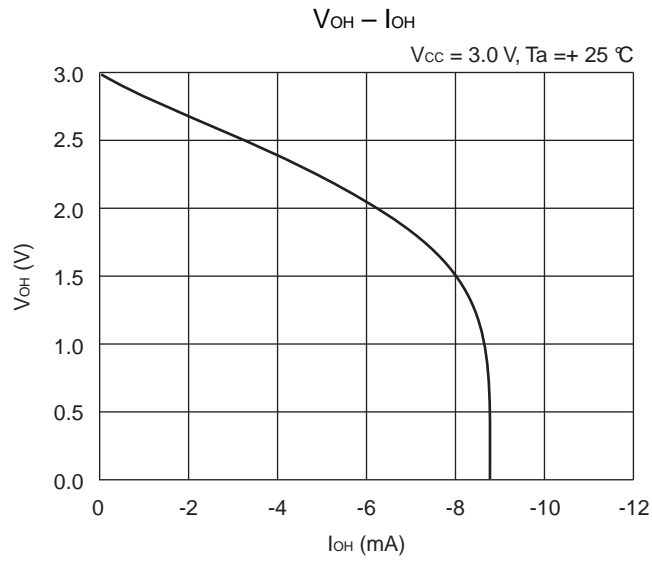
3. fin Input Impedance



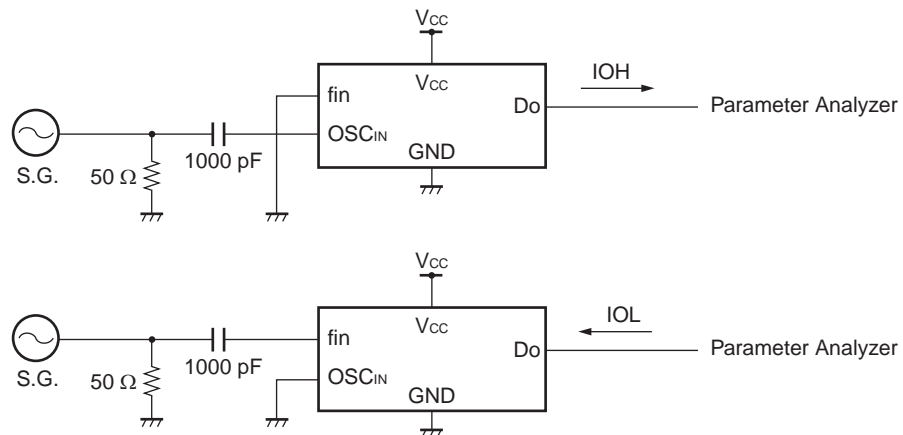
4. OSC_{IN} Input Impedance



5. Do Outut Current



Measurement Circuit



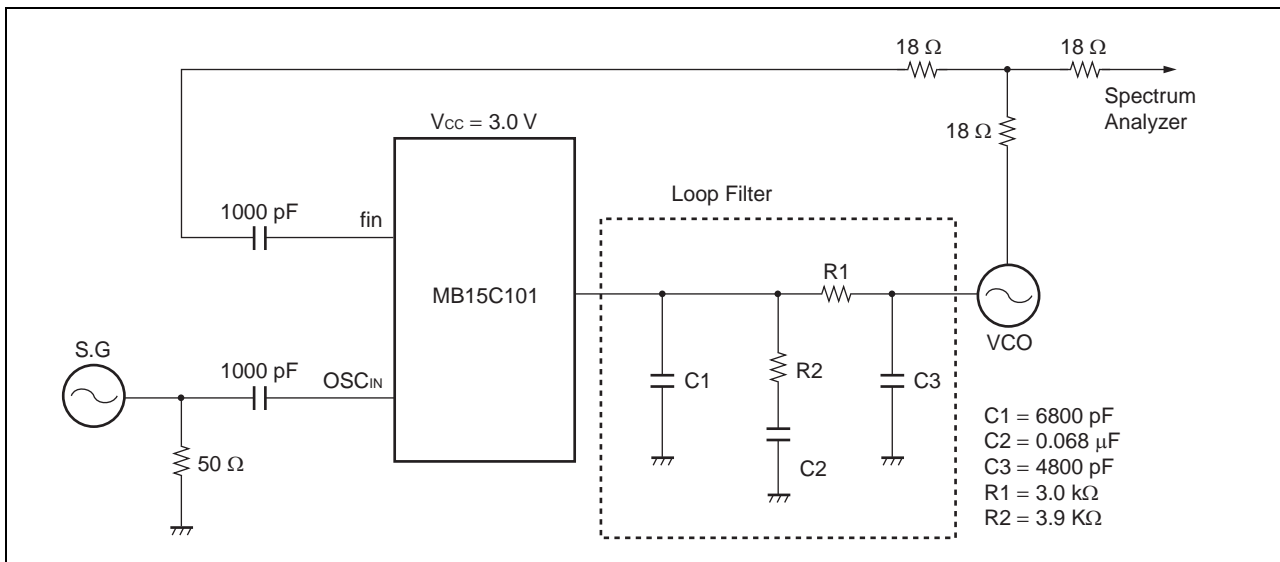
■ REFERENCE INFORMATION

1. Application Measurement

- Test Results

		Results
Lockup time ± 1 kHz		
Un lock \rightarrow Lock		2.3 ms
Power on \rightarrow Lock		3.4 ms
Reference leakage ($\Delta f = 58$ kHz)		-88.5 dBc
Phase noise	($\Delta f = 1$ kHz)	-88.0 dBc/Hz
	($\Delta f = 10$ kHz)	-111.0 dBc/Hz
	($\Delta f = 100$ kHz)	-118.0 dBc/Hz
	($\Delta f = 1$ MHz)	-134.0 dBc/Hz
V_{CC} (V)		3.0 V
VCO		Discrete VCO ($K_v = 3.5$ MHz/V) Lock Frequency = 274.0 MHz ($f_r = 58$ kHz)

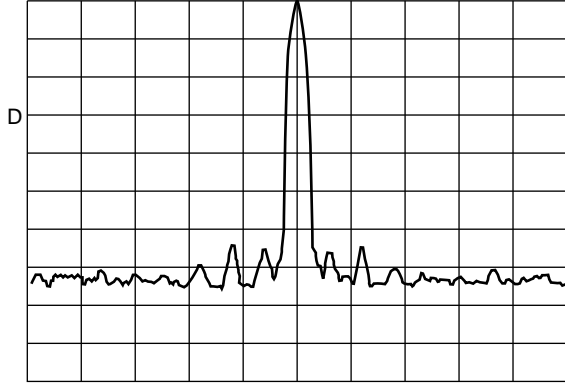
- Measurement Circuit



2. Spectrum Characteristic

$\Delta f = 1 \text{ kHz}$

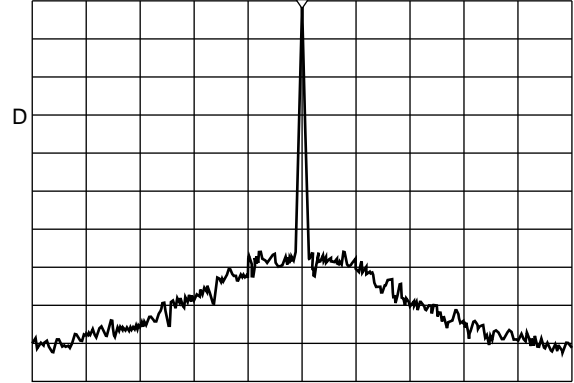
ATTEN 10dB SPAN 2.0 kHz $\Delta\text{MKR} -73.83 \text{ dB}$
 RL -1.5 dBm 10 dB/ 1.000 kHz



CENTER 273.999827 MHz SPAN 2.000 kHz
 RBW 30 Hz VBW 3.0 Hz SWP 3.00 sec

$\Delta f = 10 \text{ kHz}$

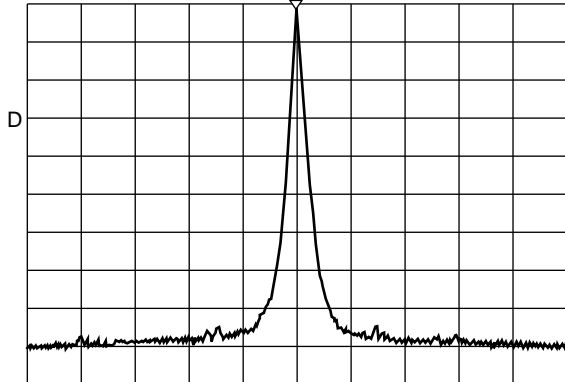
ATTEN 10dB SPAN 20 kHz $\Delta\text{MKR} -91.83 \text{ dB}$
 RL -1.5 dBm 10 dB/ 10.00 kHz



CENTER 273.999827 MHz SPAN 20.00 kHz
 RBW 100 Hz VBW 30 Hz SWP 30.0 sec

$\Delta f = 100 \text{ kHz}$

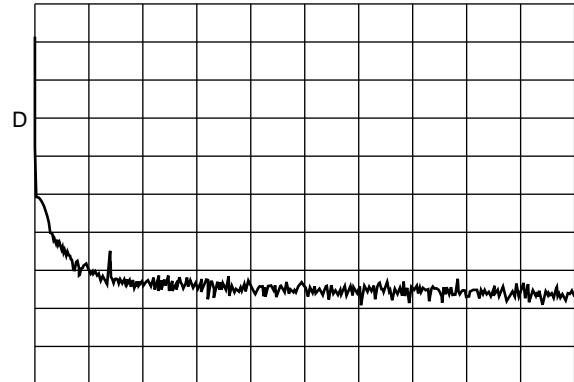
ATTEN 10 dB SPAN 200 kHz $\Delta\text{MKR} -88.50 \text{ dB}$
 RL -1.5 dBm 10 dB/ 58.0 kHz



CENTER 274.0002 MHz SPAN 200.0 kHz
 RBW 1.0 kHz VBW 30 Hz SWP 30.0 sec

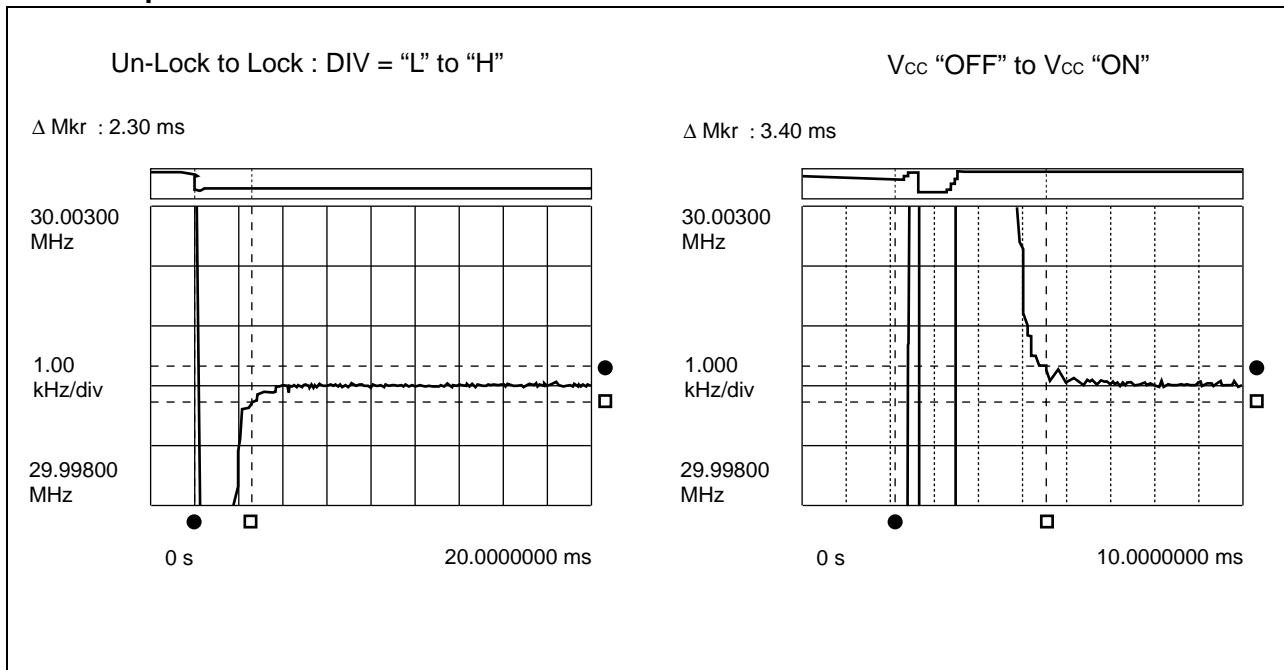
$\Delta f = 1 \text{ MHz}$

ATTEN 10dB SPAN 2 MHz $\Delta\text{MKR} -105.5 \text{ dB}$
 RL -30.0 dBm 10 dB/ 275.000 MHz



START 274.000 MHz STOP 276.000 MHz
 RBW 1.0 Hz VBW 100 Hz SWP 100 sec

3. Lockup Time: Un-Lock to Lock



■ HANDLING PRECAUTIONS

Take appropriate measures against static electricity.

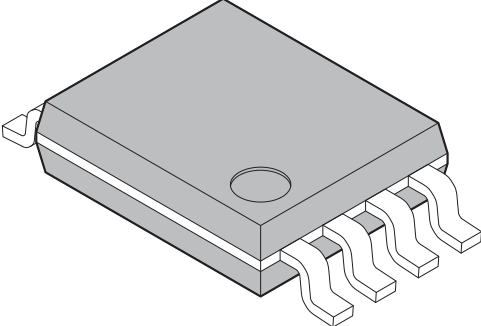
- This device should be transported and stored in anti-static containers.
- This is a static-sensitive device; take proper anti-ESD precautions. Ensure that personnel and equipment are properly grounded. Cover workbenches with grounded conductive mats.
- Always turn the power supply off before inserting or removing the device from its socket.
- Protect leads with a conductive sheet when handling or transporting PC boards with devices.

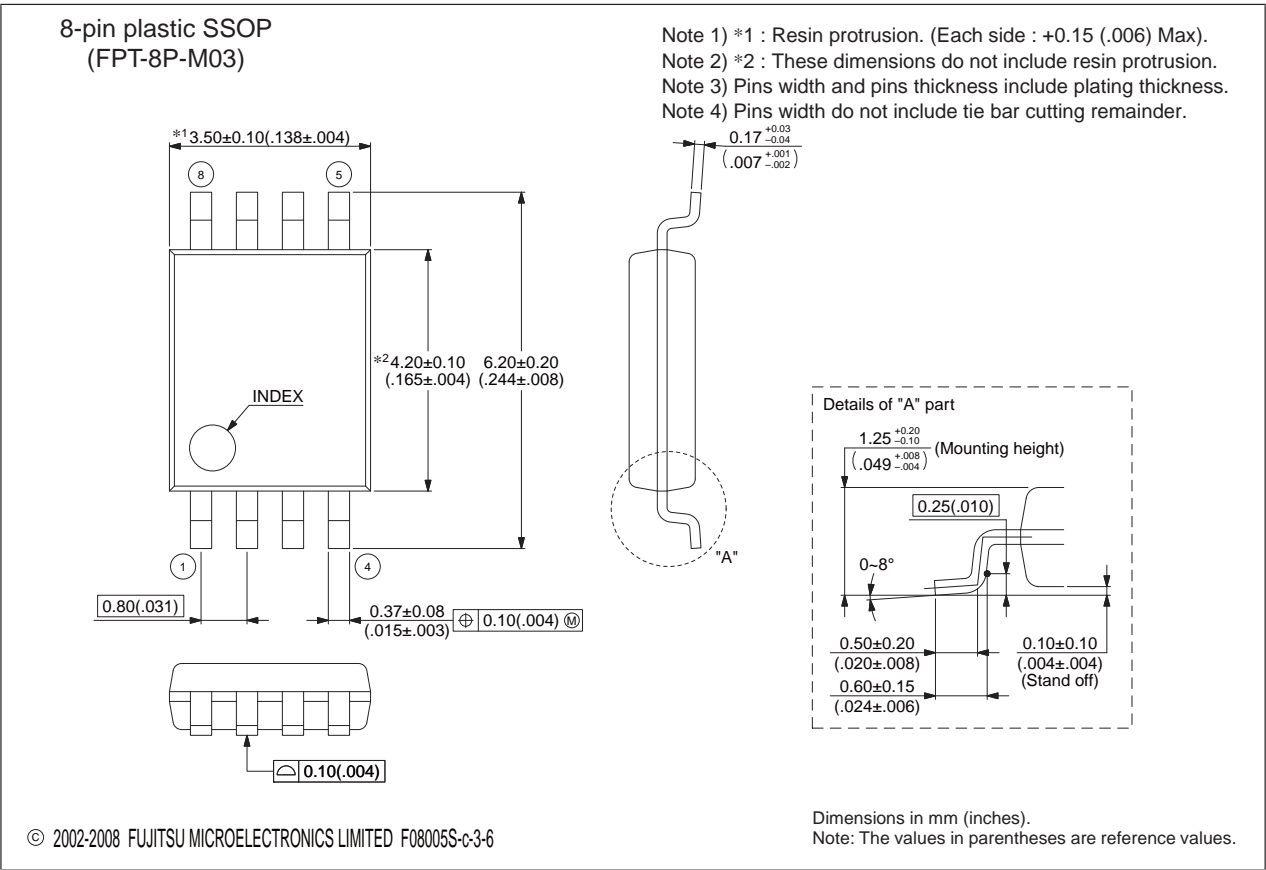
MB15C101

■ ORDERING INFORMATION

Part number	Package	Remarks
MB15C101PFV	8-pin, Plastic SSOP (FPT-8P-M03)	

PACKAGE DIMENSIONS

<p>8-pin plastic SSOP</p>  <p>(FPT-8P-M03)</p>	Lead pitch	0.80 mm
	Package width × package length	4.2 × 3.5 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	1.45 mm MAX
	Weight	0.04 g
	Code (Reference)	P-SSOP8-4.2×3.5-0.80



■ MAJOR CHANGES IN THIS EDITION

A change on a page is indicated by a vertical line drawn on the left side of that page.

Page	Section	Change Results
2	■ PIN ASSIGNMENT	Deleted the description of BCC package “LCC-16P-M06”.
	■ PIN DESCRIPTIONS	
8	■ TYPICAL CHARACTERISTICS • Measurement Circuit (for measuring input sensitivity f_{in}/OSC_{IN})	
14	■ ORDERING INFORMATION	
15	■ PACKAGE DIMENSIONS	

MEMO

MEMO

MEMO

FUJITSU SEMICONDUCTOR LIMITED

Nomura Fudosan Shin-yokohama Bldg. 10-23, Shin-yokohama 2-Chome,
Kohoku-ku Yokohama Kanagawa 222-0033, Japan

Tel: +81-45-415-5858

<http://jp.fujitsu.com/fsl/en/>

For further information please contact:

North and South America

FUJITSU SEMICONDUCTOR AMERICA, INC.

1250 E. Arques Avenue, M/S 333

Sunnyvale, CA 94085-5401, U.S.A.

Tel: +1-408-737-5600 Fax: +1-408-737-5999

<http://us.fujitsu.com/micro/>

Asia Pacific

FUJITSU SEMICONDUCTOR ASIA PTE. LTD.

151 Lorong Chuan,

#05-08 New Tech Park 556741 Singapore

Tel : +65-6281-0770 Fax : +65-6281-0220

<http://sg.fujitsu.com/semiconductor/>

Europe

FUJITSU SEMICONDUCTOR EUROPE GmbH

Pittlerstrasse 47, 63225 Langen, Germany

Tel: +49-6103-690-0 Fax: +49-6103-690-122

<http://emea.fujitsu.com/semiconductor/>

FUJITSU SEMICONDUCTOR SHANGHAI CO., LTD.

30F, Kerry Parkside, 1155 Fang Dian Road, Pudong District,

Shanghai 201204, China

Tel : +86-21-6146-3688 Fax : +86-21-6146-3660

<http://cn.fujitsu.com/fss/>

Korea

FUJITSU SEMICONDUCTOR KOREA LTD.

902 Kosmo Tower Building, 1002 Daechi-Dong,

Gangnam-Gu, Seoul 135-280, Republic of Korea

Tel: +82-2-3484-7100 Fax: +82-2-3484-7111

<http://kr.fujitsu.com/fsk/>

FUJITSU SEMICONDUCTOR PACIFIC ASIA LTD.

2/F, Green 18 Building, Hong Kong Science Park,

Shatin, N.T., Hong Kong

Tel : +852-2736-3232 Fax : +852-2314-4207

<http://cn.fujitsu.com/fsp/>

Specifications are subject to change without notice. For further information please contact each office.

All Rights Reserved.

The contents of this document are subject to change without notice.

Customers are advised to consult with sales representatives before ordering.

The information, such as descriptions of function and application circuit examples, in this document are presented solely for the purpose of reference to show examples of operations and uses of FUJITSU SEMICONDUCTOR device; FUJITSU SEMICONDUCTOR does not warrant proper operation of the device with respect to use based on such information. When you develop equipment incorporating the device based on such information, you must assume any responsibility arising out of such use of the information.

FUJITSU SEMICONDUCTOR assumes no liability for any damages whatsoever arising out of the use of the information.

Any information in this document, including descriptions of function and schematic diagrams, shall not be construed as license of the use or exercise of any intellectual property right, such as patent right or copyright, or any other right of FUJITSU SEMICONDUCTOR or any third party or does FUJITSU SEMICONDUCTOR warrant non-infringement of any third-party's intellectual property right or other right by using such information. FUJITSU SEMICONDUCTOR assumes no liability for any infringement of the intellectual property rights or other rights of third parties which would result from the use of information contained herein.

The products described in this document are designed, developed and manufactured as contemplated for general use, including without limitation, ordinary industrial use, general office use, personal use, and household use, but are not designed, developed and manufactured as contemplated (1) for use accompanying fatal risks or dangers that, unless extremely high safety is secured, could have a serious effect to the public, and could lead directly to death, personal injury, severe physical damage or other loss (i.e., nuclear reaction control in nuclear facility, aircraft flight control, air traffic control, mass transport control, medical life support system, missile launch control in weapon system), or (2) for use requiring extremely high reliability (i.e., submersible repeater and artificial satellite).

Please note that FUJITSU SEMICONDUCTOR will not be liable against you and/or any third party for any claims or damages arising in connection with above-mentioned uses of the products.

Any semiconductor devices have an inherent chance of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

Exportation/release of any products described in this document may require necessary procedures in accordance with the regulations of the Foreign Exchange and Foreign Trade Control Law of Japan and/or US export control laws.

The company names and brand names herein are the trademarks or registered trademarks of their respective owners.

Edited: Sales Promotion Department